



#### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
80V	5.2m $\Omega$ @10V	110A

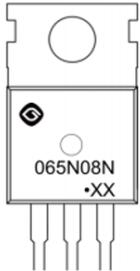
#### Feature

- Split Gate Trench Technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

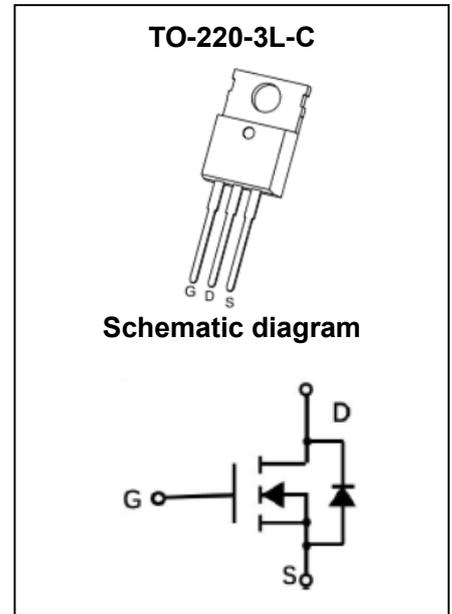
#### Application

- Industrial Power Supply
- Load Switch

#### MARKING:



065N08N = Device Code  
XX = Date Code  
Solid Dot = Green Indicator



#### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DS}$	80	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D$	110	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	440	A
Single Pulsed Avalanche Current <sup>3</sup>	$I_{AS}$	35	A
Single Pulsed Avalanche Energy <sup>3</sup>	$E_{AS}$	305	mJ
Power Dissipation <sup>5</sup>	$P_D$	208	W
Thermal Resistance from Junction to Ambient <sup>6</sup>	$R_{\theta JA}$	60	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.6	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

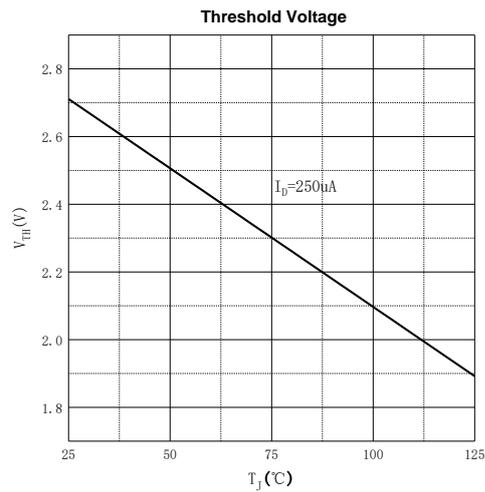
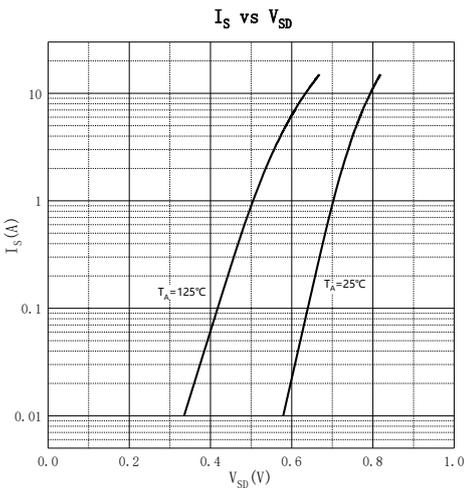
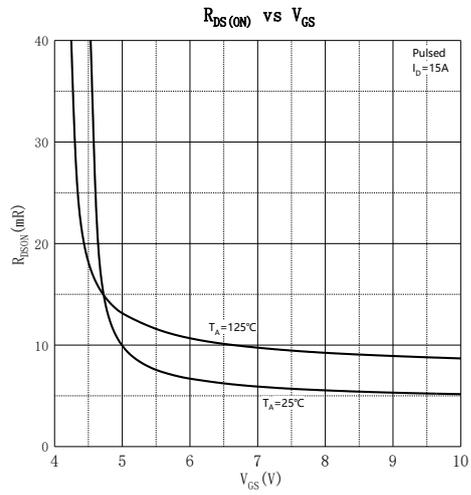
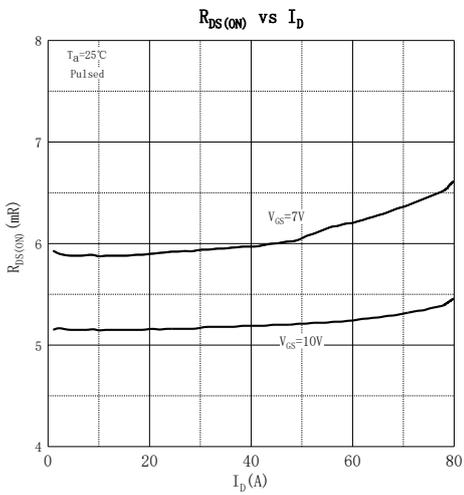
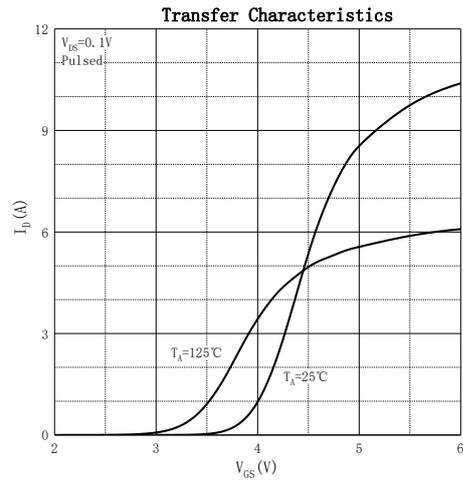
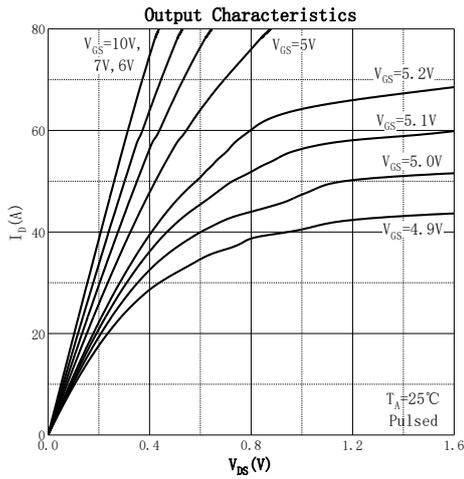
## MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

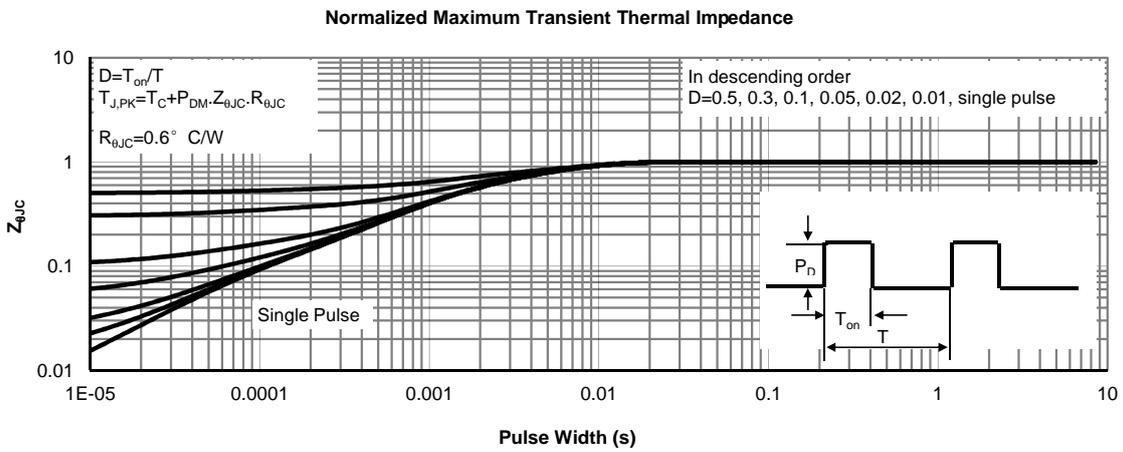
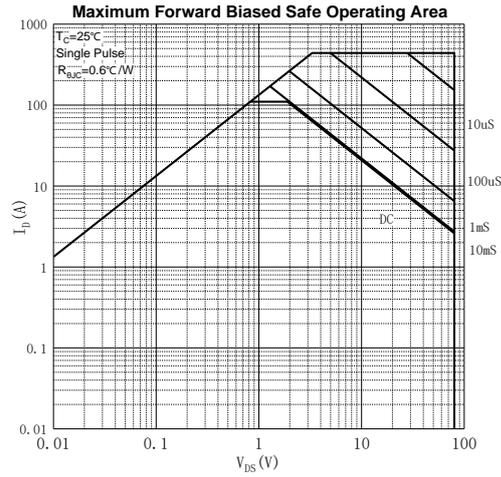
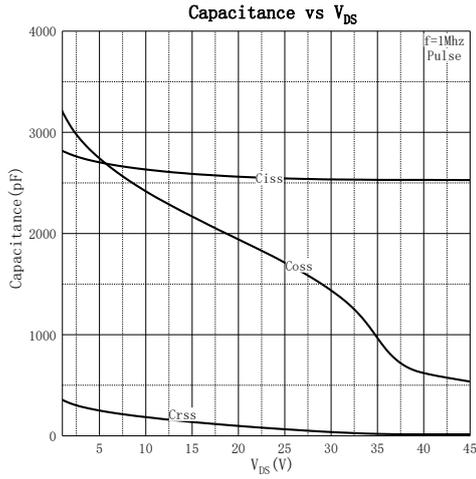
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	80			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80V, V_{GS} = 0V$			1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>4</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 15A$		5.2	6.5	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 5V, I_D = 15A$	10			S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 40V, V_{GS} = 0V, f = 1MHz$		2535		pF
Output Capacitance	$C_{oss}$			570		
Reverse Transfer Capacitance	$C_{rss}$			15		
Gate Resistance	$R_g$	$V_{DS} = 40V, V_{GS} = 0V, f = 1MHz$		2		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 40V, V_{GS} = 10V, I_D = 15A$		39		nC
Gate-source Charge	$Q_{gs}$			9		
Gate-drain Charge	$Q_{gd}$			10.5		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 40V, V_{GS} = 10V, R_L = 2\Omega$ $R_G = 3\Omega$		18		ns
Turn-on Rise Time	$t_r$			11		
Turn-off Delay Time	$t_{d(off)}$			38		
Turn-off Fall Time	$t_f$			9		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 15A$			1.2	V

Notes :

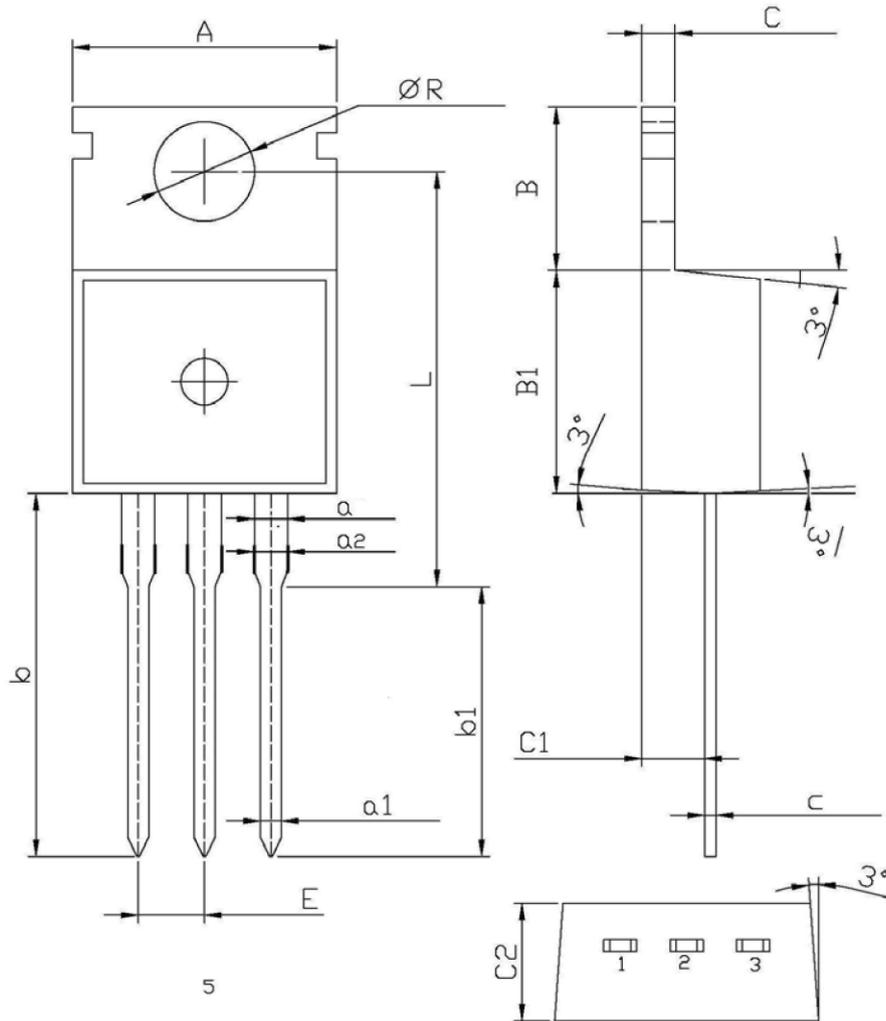
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 40V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Characteristics





## TO-220-3L-C Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.800	10.200	0.386	0.402
R	3.560	3.640	0.140	0.143
L	15.700	16.100	0.618	0.634
b	12.600	13.600	0.496	0.535
b1	9.600	10.600	0.378	0.417
a	1.220	1.320	0.048	0.052
E	2.340	2.740	0.092	0.108
a2	1.250	1.450	0.049	0.057
C	1.200	1.400	0.047	0.055
B	6.300	6.700	0.248	0.264
B1	9.000	9.400	0.354	0.370
C1	2.200	2.600	0.087	0.102
a1	0.700	0.900	0.028	0.035
c	0.400	0.600	0.016	0.024
C2	4.300	4.700	0.169	0.185